EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(method and fabricating and three-dimensional and integrated and device and including and plurality and vertically and stacked and interconnected and wafers and comprising and steps and first and front and surface and back and formed and region and adjaeent and via and being and characterized and lateral and dimension and front and surface and removing and material and from and opening and greater and conducting and material and second and stud and bonding and material and projecting and align layer and makes and contact and further and extending and characterized).clm.	US-PGPUB	OR	ON	2008/01/03 16:05

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